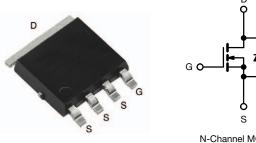
Vishay Siliconix



E Series Power MOSFET

PRODUCT SUMMA	RY		
V _{DS} (V) at T _J max.	700)	
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 V$	0.755	
Q _g max. (nC)	32		
Q _{gs} (nC)	5		
Q _{gd} (nC)	7		
Configuration	Single		

PowerPAK[®] SO-8L



N-Channel MOSFET

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Consumer
 - Adaptors

ORDERING INFORMATION	
Package	PowerPAK SO-8L
Lead (Pb)-free and Halogen-free	SiHJ6N65E-T1-GE3

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unl	ess otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V _{DS}	650	V
Gate-Source Voltage			V _{GS}	± 30	
Continuous Drain Current (T ₁ = 150 °C)	V _{GS} at 10 V	T _C = 25 °C	- I _D	5.6	
Continuous Drain Current $(1_j = 150^{\circ} C)$	V _{GS} at 10 V	T _C = 100 °C		3.6	А
Pulsed Drain Current ^a			I _{DM}	12	
Linear Derating Factor				0.76	W/°C
Single Pulse Avalanche Energy ^b			E _{AS}	36	mJ
Maximum Power Dissipation			PD	74	W
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C
Drain-Source Voltage Slope T _J = 125 °C			dV/dt	70	V/ns
Reverse Diode dV/dt ^c				9.4	v/ns

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature.

b. V_{DD} = 120 V, starting T_J = 25 °C, L = 28.2 mH, R_q = 25 Ω , I_{AS} = 1.6 A.

c. $I_{SD} \leq I_D$, dI/dt = 100 A/µs, starting T_J = 25 °C.

THERMAL RESISTANCE RATI	NGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R _{thJA}	52	65	°C/W
Maximum Junction-to-Case (Drain)	R _{thJC}	1.2	1.7	0/10

S16-0840-Rev. B, 09-May-16

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PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static		-					
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 250 μA	650	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I _D = 1 mA	-	0.8	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	· V _{GS} , I _D = 250 μA	2.0	-	4.0	V
Cata Source Leakage	I	\	$V_{\rm GS} = \pm 20 \text{ V}$	-	-	± 100	nA
Gate-Source Leakage	I _{GSS}	١	$V_{\rm GS}$ = ± 30 V	-	-	± 1	μA
Zara Cata Valtaga Drain Current	I	V _{DS} =	650 V, V _{GS} = 0 V	-	-	1	
Zero Gate Voltage Drain Current	IDSS	V _{DS} = 520 V	', V _{GS} = 0 V, T _J = 125 °C	-	-	10	μA
Drain-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 10 V$	I _D = 3 A	-	0.755	0.868	Ω
Forward Transconductance	g _{fs}	V _{DS}	= 30 V, I _D = 3 A	-	1.8	-	S
Dynamic		•			•	•	
Input Capacitance	C _{iss}		V _{GS} = 0 V,	-	596	-	
Output Capacitance	C _{oss}	· ·	$V_{\rm DS} = 100 {\rm V},$	-	35	-	
Reverse Transfer Capacitance	C _{rss}		f = 1 MHz	-	4	-	
Effective Output Capacitance, Energy Related ^a	C _{o(er)}		(), 500 V V 0 V	-	26	-	pF
Effective Output Capacitance, Time Related ^b	C _{o(tr)}	$v_{\rm DS} = 0.0$	/ to 520 V, V _{GS} = 0 V	-	90	-]
Total Gate Charge	Qg			-	16	32	
Gate-Source Charge	Q _{gs}	$V_{GS} = 10 V$	$I_D = 3 \text{ A}, V_{DS} = 520 \text{ V}$	-	5	-	nC
Gate-Drain Charge	Q _{gd}			-	7	-	
Turn-On Delay Time	t _{d(on)}			-	14	28	
Rise Time	t _r	V _{DD} = 520 V, I _D = 3 A,		-	14	28	-
Turn-Off Delay Time	t _{d(off)}	V _{GS} =	= 10 V, R _g = 9.1 Ω	-	25	50	ns
Fall Time	t _f			-	17	34	
Gate Input Resistance	Rg		f = 1 MHz	0.4	0.8	1.6	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	showing the	MOSFET symbol showing the		-	5.6	
Pulsed Diode Forward Current	I _{SM}	p - n junction diode		-	-	12	- A
Diode Forward Voltage	V _{SD}	T _J = 25 °	C, I _S = 3 A, V _{GS} = 0 V	-	0.9	1.2	V
Reverse Recovery Time	t _{rr}			- 1	278	556	ns
Reverse Recovery Charge	Q _{rr}	$T_J = 2$	5 °C, I _F = I _S = 3 A, 100 A/µs ^{, V} _B = 25 V	-	2.1	4.2	μC
Reverse Recovery Current	I _{RRM}	di/dt =	100 A/μs [,] * _R = 25 V	-	12	-	A

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

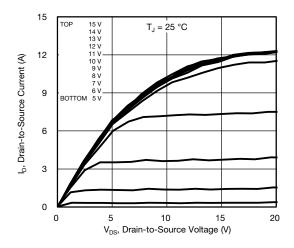


Fig. 1 - Typical Output Characteristics

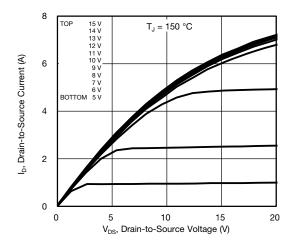
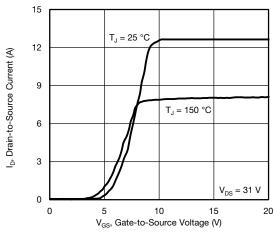


Fig. 2 - Typical Output Characteristics





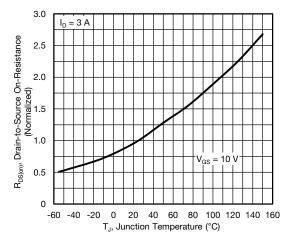


Fig. 4 - Normalized On-Resistance vs. Temperature

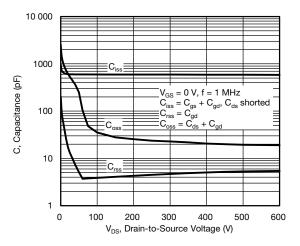


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

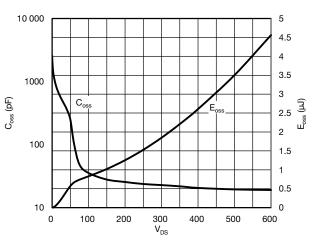


Fig. 6 - $C_{\rm oss}$ and $E_{\rm oss}$ vs. $V_{\rm DS}$

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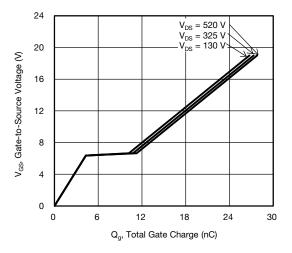


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

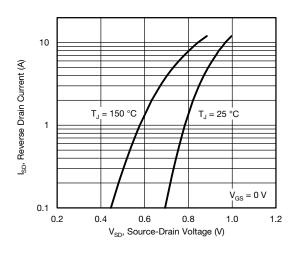


Fig. 8 - Typical Source-Drain Diode Forward Voltage

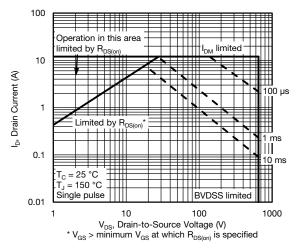


Fig. 9 - Maximum Safe Operating Area

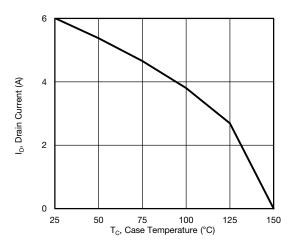


Fig. 10 - Maximum Drain Current vs. Case Temperature

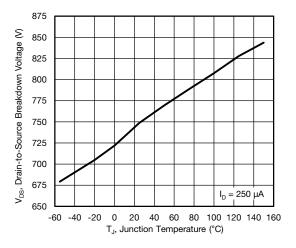
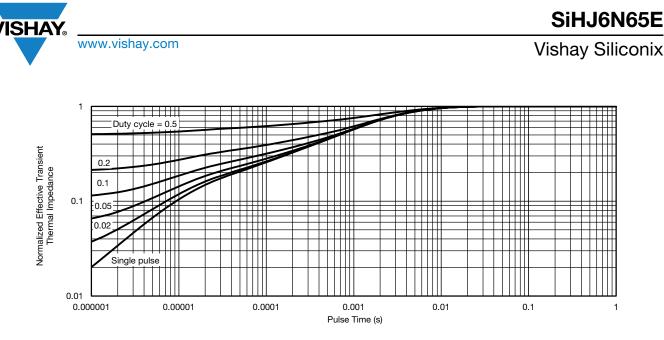


Fig. 11 - Temperature vs. Drain-to-Source Voltage

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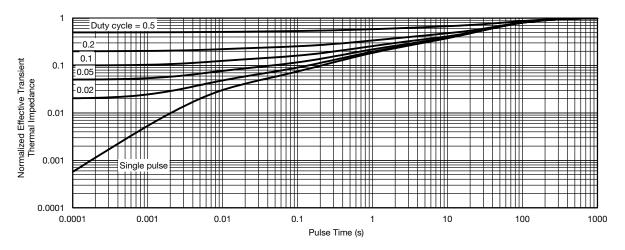


Fig. 13 - Normalized Thermal Transient Impedance, Junction-to-Ambient

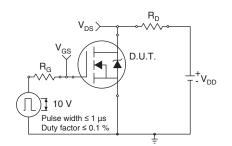


Fig. 14 - Switching Time Test Circuit

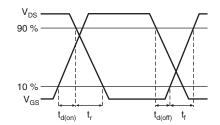


Fig. 15 - Switching Time Waveforms

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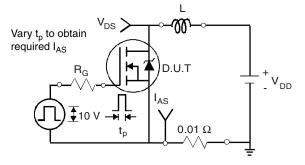


Fig. 16 - Unclamped Inductive Test Circuit

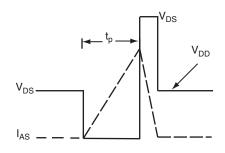


Fig. 17 - Unclamped Inductive Waveforms

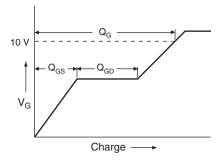


Fig. 18 - Basic Gate Charge Waveform

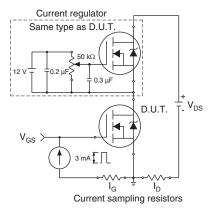


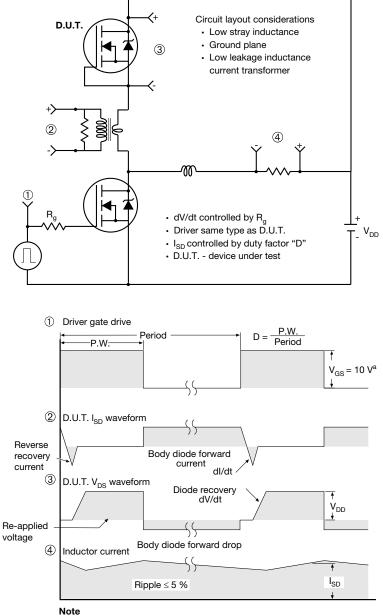
Fig. 19 - Gate Charge Test Circuit



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Peak Diode Recovery dV/dt Test Circuit



a. $V_{GS} = 5$ V for logic level devices

Fig. 20 - For N-Channel

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Package Information



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DIM.	MILLIMETERS			INCHES			
	MIN.	NOM.	MAX.	MIN.	N. NOM.		
А	1.00	1.07	1.14	0.039	0.042	0.045	
A1	0.00	-	0.127	0.00	-	0.005	
b	0.33	0.41	0.48	0.013	0.016	0.019	
b1	0.44	0.51	0.58	0.017	0.020	0.023	
b2	4.80	4.90	5.00	0.189	0.193	0.197	
b3		0.094			0.004		
b4		0.47			0.019		
С	0.20	0.25	0.30	0.008	0.010	0.012	
D	5.00	5.13	5.25	0.197	0.202	0.207	
D1	4.80	4.90	5.00	0.189	0.193	0.197	
D2	3.86	3.96	4.06	0.152	0.156	0.160	
D3	1.63	1.73	1.83	0.064	0.068	0.072	
е		1.27 BSC		0.050 BSC			
E	6.05	6.15	6.25	0.238	0.242	0.246	
E1	4.27	4.37	4.47	0.168	0.172	0.176	
E2	2.75	2.85	2.95	0.108	0.112	0.116	
F	-	-	0.15	-	-	0.006	
L	0.62	0.72	0.82	0.024	0.028	0.032	
L1	0.92	1.07	1.22	0.036	0.042	0.048	
К		0.51			0.020		
W	0.23			0.009			
W1	0.41			0.016			
W2	2.82			0.111			
W3		2.96			0.117		
θ	0°	-	10°	0°	-	10°	

Note

• Millimeters will govern



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RECOMMENDED MINIMUM PAD FOR PowerPAK[®] SO-8L SINGLE



Recommended Minimum Pads Dimensions in mm (inches)

Revision: 07-Feb-12



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